

# Contents

<b>Abstract</b>	<b>vii</b>
<b>Zusammenfassung</b>	<b>ix</b>
<b>List of symbols and abbreviations</b>	<b>xv</b>
<b>1 Introduction</b>	<b>1</b>
1.1 Motivation . . . . .	1
1.2 State of the art . . . . .	2
1.2.1 Microseismic and acoustic emission sensors . . . . .	2
1.2.2 Broadband mechanical amplitude amplification . . . . .	8
1.3 Objectives and organization of thesis . . . . .	11
<b>2 Theory and modeling</b>	<b>15</b>
2.1 Concept . . . . .	15
2.2 Multi-DOF mass-spring system . . . . .	16
2.2.1 Equations of motion . . . . .	17
2.2.2 Frequency response . . . . .	19
2.2.3 Time response . . . . .	22
2.2.4 Energy and dissipation . . . . .	25
2.2.5 Summary: Lumped element model assumptions . . . . .	26
<b>3 Methods</b>	<b>31</b>
3.1 Simulation . . . . .	31
3.1.1 Lumped element model . . . . .	31
3.1.2 Finite element analysis . . . . .	32
3.2 Fabrication technology . . . . .	33
3.2.1 Etch trench profile angle . . . . .	34
3.2.2 Micrograss formation . . . . .	34
3.2.3 Aspect ratio dependent etching . . . . .	34
3.2.4 Notching . . . . .	35
3.2.5 Summary of process characteristics . . . . .	36
3.3 Fabrication processes . . . . .	39
3.3.1 1-level fabrication process . . . . .	39
3.3.2 2-level fabrication process . . . . .	40

## Contents

3.4	Characterization . . . . .	45
3.4.1	Setup . . . . .	45
3.4.2	Steady-state response measurements . . . . .	47
3.4.3	Transient response measurements . . . . .	48
<b>4</b>	<b>Proof-of-concept device</b>	<b>51</b>
4.1	Device design . . . . .	51
4.2	Fabrication results . . . . .	51
4.3	Characterization results . . . . .	53
4.3.1	Steady-state response . . . . .	53
4.3.2	Transient response . . . . .	58
4.4	Discussion . . . . .	62
4.4.1	Device design and fabrication . . . . .	62
4.4.2	Comparison of measurements and simulation . . . . .	62
4.4.3	Amplitude-amplification with coupled mass-spring system . . . . .	63
4.5	Summary . . . . .	63
<b>5</b>	<b>Amplification and bandwidth design</b>	<b>65</b>
5.1	Introduction . . . . .	65
5.2	Amplification-bandwidth product . . . . .	65
5.3	Design rules . . . . .	66
5.4	Device design . . . . .	70
5.5	Fabrication results . . . . .	71
5.6	Characterization results . . . . .	71
5.6.1	Steady-state response . . . . .	72
5.6.2	Transient response . . . . .	73
5.7	Discussion . . . . .	76
5.7.1	Device design and fabrication . . . . .	76
5.7.2	Comparison of measurements and simulation . . . . .	76
5.7.3	Amplification and bandwidth tuning by design . . . . .	77
5.8	Summary . . . . .	77
<b>6</b>	<b>Upscaled device</b>	<b>79</b>
6.1	Device design . . . . .	79
6.1.1	Spring design . . . . .	80
6.1.2	Spring positioning and mass design . . . . .	85
6.1.3	Capacitive readout design . . . . .	87
6.1.4	Frequency matching . . . . .	87
6.1.5	Final device design . . . . .	87
6.2	Fabrication results . . . . .	91

6.3	Characterization results . . . . .	93
6.3.1	Steady-state response . . . . .	94
6.3.2	Transient response . . . . .	95
6.3.3	Influence of pressure . . . . .	98
6.3.4	Repeatability . . . . .	98
6.4	Discussion . . . . .	100
6.4.1	Device design . . . . .	100
6.4.2	Device fabrication . . . . .	100
6.4.3	Comparison of measurements and simulations . . . . .	101
6.4.4	Device performance . . . . .	102
6.4.5	Summary . . . . .	103
<b>7</b>	<b>Discussion</b>	<b>105</b>
7.1	Application in an ultra-low power MS/AE MEMS trigger . . . . .	105
7.2	Targeted bandwidth and amplification . . . . .	105
7.3	Detection of low signal amplitudes . . . . .	109
<b>8</b>	<b>Conclusion and outlook</b>	<b>113</b>
	<b>Appendix</b>	<b>116</b>
A	Data sheets of commercial MS/AE sensors . . . . .	117
B	Capacitive readout . . . . .	129
C	Eigenvalues . . . . .	131
D	Failure mode and effects analysis . . . . .	133
E	Data sheets of actuators . . . . .	140
F	Out-of-plane deformation in proof-of-concept device . . . . .	142
G	Different mass geometries with corresponding spring positions . . . . .	143
H	Analytic spring stiffnesses . . . . .	144
I	Process Runsheets . . . . .	147
I.1	1-level out-of-plane fabrication process . . . . .	147
I.2	1-level in-plane fabrication process . . . . .	148
I.3	2-level fabrication process . . . . .	149
	<b>Bibliography</b>	<b>151</b>
	<b>Acknowledgement</b>	<b>161</b>
	<b>Publications</b>	<b>163</b>
	<b>Student projects</b>	<b>165</b>
	<b>Curriculum vitae</b>	<b>167</b>